

IN THE TITLE

Please delete the title in its entirety and insert --- DEVICE WITH SEGMENTED BALL LIMITING METALLURGY --- therein.

IN THE CLAIMS

Please cancel non-elected claims 16/25.

Please enter the pending claims as follows:

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1. (Unchanged) A device having Input/Output (I/O) connections to a package or board comprising :  
bond pads,  
BLM disposed over said bond pads, said BLM having two or more segments, and  
a bump disposed over said segments.
  2. (Once Amended) The device of claim 1 wherein said bump comprises a Lead-Tin (Pb-Sn) solder.
  3. (Once Amended) The device of claim 1 wherein said bump is free of Lead (Pb).

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4. (Once Amended) The device of claim 1 wherein said bump comprises a Tin-Silver-Copper (Sn-Ag-Cu) ternary alloy.
  5. (Once Amended) The device of claim 1 wherein said bump comprises an Electrically Conductive Adhesive (ECA).
  6. (Unchanged) The device of claim 1 wherein said BLM provides a diffusion barrier to metals.
  7. (Unchanged) The device of claim 1 wherein said BLM comprises a lower layer and an upper layer.
  8. (Unchanged) The device of claim 7 wherein said lower layer comprises Titanium (Ti) with a thickness of about 200 to 1500 Angstroms.
  9. (Unchanged) The device of claim 7 wherein said upper layer comprises Nickel-Vanadium (Ni-V) with a thickness of about 1000 to 8000 Angstroms.
  10. (Unchanged) The device of claim 1 wherein said segments comprise a substantially polygonal layout.

11. (Unchanged) The device of claim 1 further comprising vias, wherein a segment is electrically connected to two or more of said vias.
12. (Unchanged) The device of claim 11, wherein said vias are laterally offset from a center of said bump to which they are electrically connected.
13. (Unchanged) The device of claim 11 wherein said vias comprise a substantially polygonal layout.
14. (Once Amended) The device of claim 4, wherein each of said segments is electrically connected to two or more of said bond pads.
15. (Unchanged) The device of claim 14 wherein said bond pads are laterally offset from a center of said bump to which they are electrically connected.
26. (Unchanged) A device having I/O connections to a package or board comprising :  
a bond pad, said bond pad having two or more segments, and  
a wire lead attached to said segments.

27. (Unchanged) The device of claim 26 further comprising vias, wherein a segment is electrically connected to two or more of said vias.

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28. (Unchanged) The device of claim 26 further comprising lines, wherein a segment is electrically connected to two or more of said lines.